

COMPLIANT

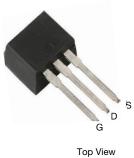
## F2804L-VB TO262 Datasheet N-Channel 40-V (D-S) 175 °C MOSFET

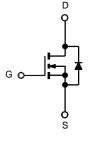
**FEATURES** 

Trench Power MOSFET
175 °C Junction Temperature

PRODUCT SUMMARY				
V <sub>(BR)DSS</sub> (V)	r <sub>DS(on)</sub> (∧)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
40	0.005 at V <sub>GS</sub> = 10 V	100	95	

TO-262





• High Threshold Voltage at High Temperature

N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	40	v	
Gate-Source Voltage		V <sub>GS</sub>	V <sub>GS</sub> 20		
Continuous Drain Current ( $T_1 = 175 \ ^{\circ}C$ )	T <sub>C</sub> = 25 °C	1_	110		
Continuous Drain Current (Tj = 175°C)	T <sub>C</sub> = 125 °C		70		
Pulsed Drain Current		I <sub>DM</sub>	300	- A	
Avalanche Current		I <sub>AR</sub>	50	7	
Repetitive Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AR</sub>	125	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	P	150 <sup>b</sup>		
	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	3.75	- W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

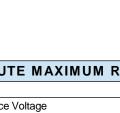
THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case		R <sub>thJC</sub>	1		

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).



<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{DS} = 0 V, I_{D} = 250 \mu A$	40			v	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.0	2.0	4.0		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 V, V_{GS} = 0 V$			1	μΑ	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50		
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	120			А	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.005			
	r <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}, T_J = 125 ^{\circ}\text{C}$		0.008			
		$V_{GS}$ = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C		0.0106		1	
Forward Transconductance <sup>a</sup>	<b>g</b> fs	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A	20	50		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		3200		pF	
Output Capacitance	C <sub>oss</sub>			600			
Reverse Transfer Capacitance	C <sub>rss</sub>			320			
Total Gate Charge <sup>c</sup>	Qg			95		nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		37			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			21			
Gate Resistance	Rg	f = 1.0 MHz		1.7		^	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	30	ns	
Rise Time <sup>c</sup>	tr	$V_{DD}$ = 20 V, R <sub>L</sub> = 0.4 $\land$ I <sub>D</sub> $\cong$ 50 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 2.5 $\land$		95	145		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			50	75		
Fall Time <sup>c</sup>	t <sub>f</sub>			12	20		
Source-Drain Diode Ratings and Cha	aracteristics T	c = 25 °C <sup>b</sup>	1				
Continuous Current	I <sub>S</sub>				100	•	
Pulsed Current	I <sub>SM</sub>				300	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	$I_F = 30 \text{ A}, V_{GS} = 0 \text{ V}$		0.90	1.50	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 30 A, di/dt = 100 A/μs		40	60	ns	

Notes:

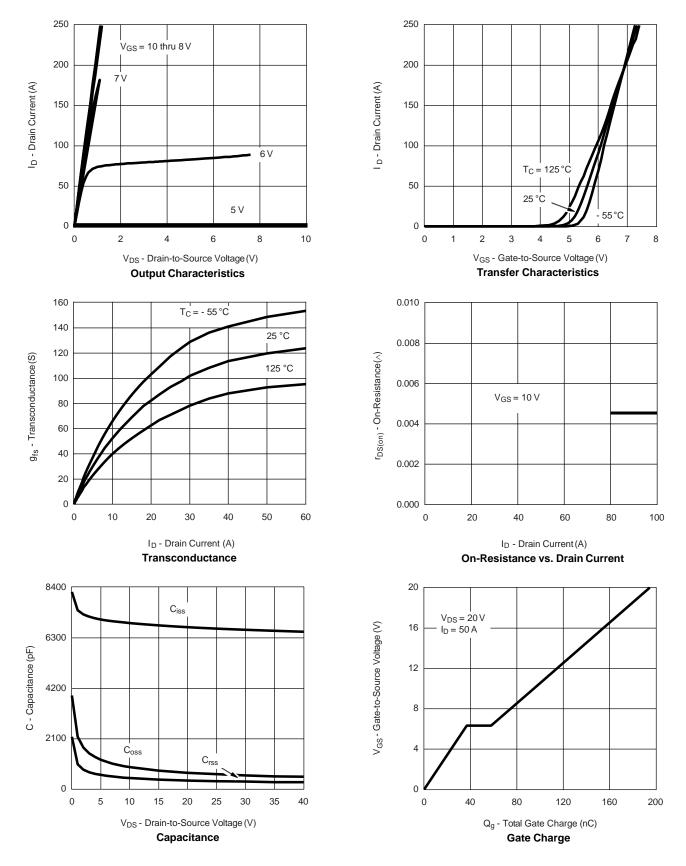
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.

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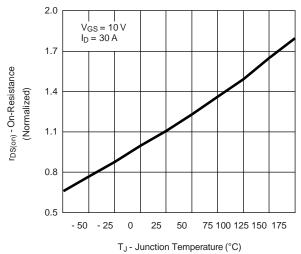


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

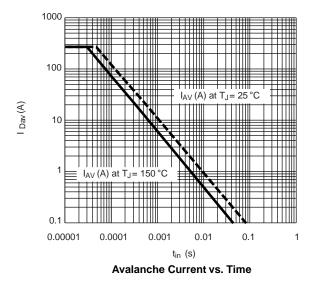


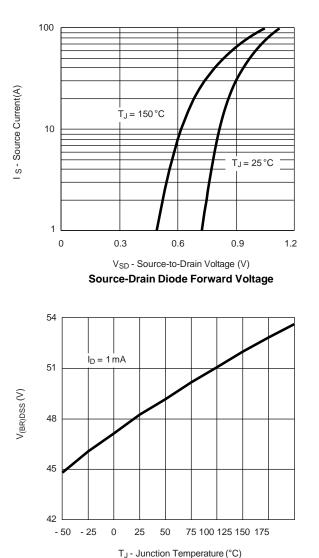


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On-Resistance vs. Junction Temperature



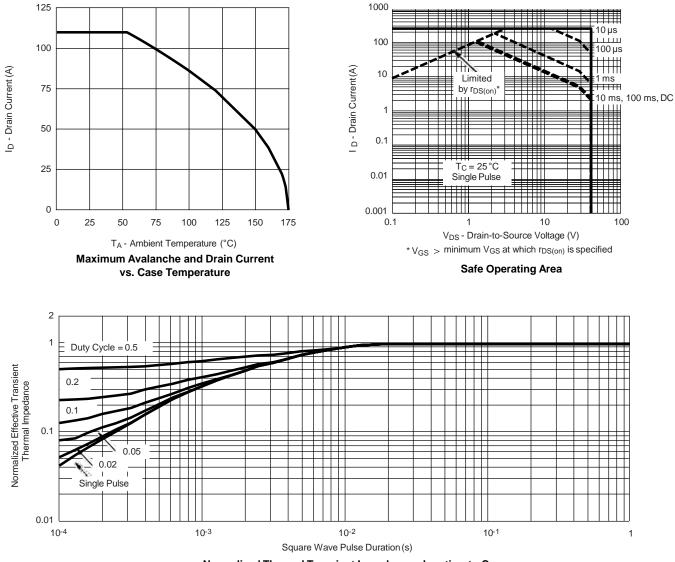


Drain Source Breakdown vs. Junction Temperature

## F2804L-VB TO262



#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



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